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SPECIFICATION FOR LCD MODULE

MODULE NO: AFK240320A0-2.7N3NTM REVISION NO: V01

Customer's Approval:					
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	SIGNATURE	DATE			
PREPARED BY (RD ENGINEER)					
CHECKED BY					
APPROVED BY					

Records of Revision

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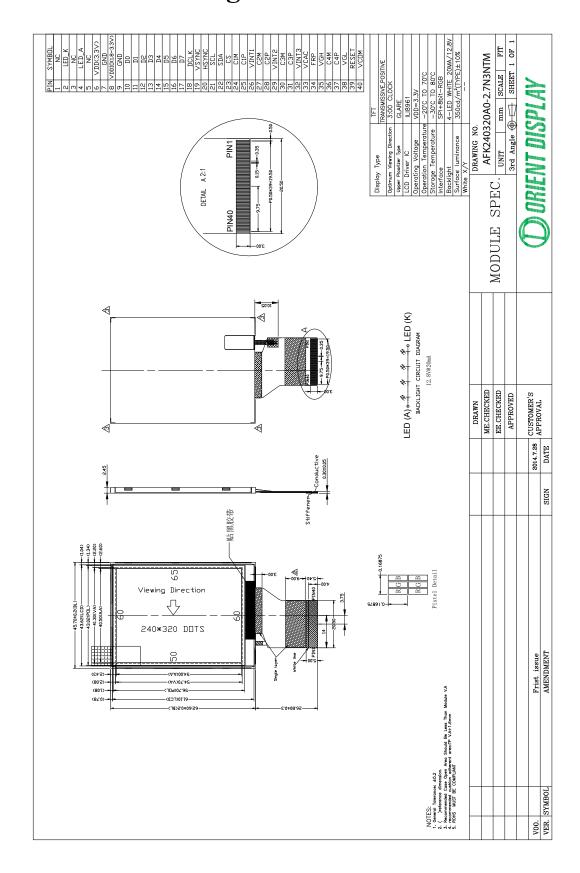
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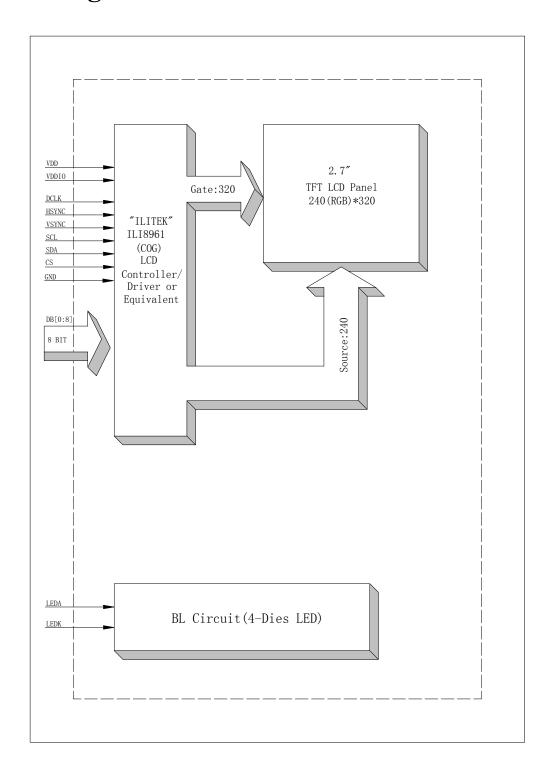
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	45.70*62.60*2.45	MM
ACTIVE SIZE (W*H)	40.50*54.00	MM
PIXEL PITCH (W*H)	0.16875*0.16875	MM
NUMBER OF DOTS	240*320	
DIVER IC	ILI8961	
INTERFACE TYPE	SPI+8 BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	3	O'CLOCK
GRAY SCALE INVERSION DIRECTION	9	O'CLOCK
COLORS	262K	
BACKLIGHT TYPE	4-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



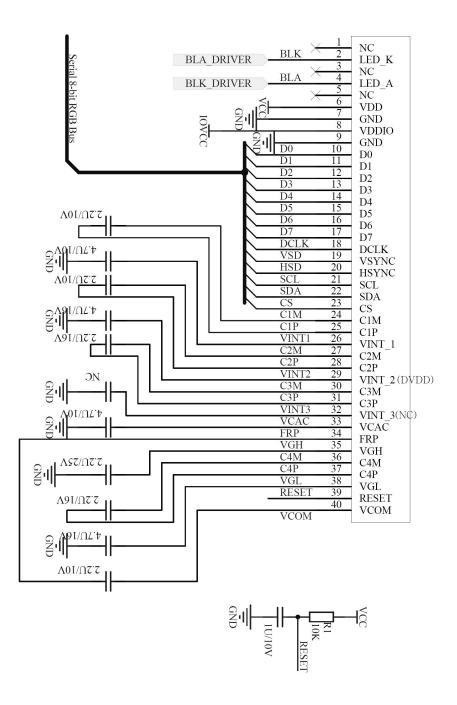
3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description			
1	NC	No Connect			
2	LED_K	Cathode of backlight			
3	NC	No Connect			
4	LED_A	Anode of backlight			
5	NC	No Connect			
6	VDD(3.3V)	Power supply			
7	GND	Ground			
8	VDDIO(1.8-3.3V)	Power supply for digital			
9	GND	Ground			
10	D0	Data bus			
11	D1	Data bus			
12	D2	Data bus			
13	D3	Data bus			
14	D4	Data bus			
15	D5	Data bus			
16	D6	Data bus			
17	D7	Data bus			
18	DCLK	Pixel clock signal in RGB interface.			
19	VSYNC	Vertical signal in RGB interface.			
20	HSYNC	Horizon signal in RGB interface			
21	SCL	Serial clock input signal			
22	SDA	Serial data input signal			
23	CS	Chip select signal			
24	C1M				
25	C1P				
26	VINT1				
27	C2M				
28	C2P	Pins to connect capacitors for power circuit			
29	VINT2	ins to connect capacitors for power encur			
30	C3M				
31	C3P				
32	VINT3				
33	VCAC				
34	FRP	Frame polarity output(Capacitor connect to VCOM)			
35	VGH	Positive power supply for gate driver(+18v)			
36	C4M	Pins to connect canacitors for nower circuit			
37	C4P	Pins to connect capacitors for power circuit			
38	VGL	Negative power supply for gate driver(-16v)			
39	RESET	Reset signal			
40	VCOM	VCOM pin			

Application circuit:



5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.6	V
Supply voltage for logic	VDDIO	-0.3	4.6	V
Supply current (One LED)	I_{LED}		30	mA
Operating temperature	Тор	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	2.5	2.8	3.3	V	
Supply Voltage for Logic	VDDIO	1.65	1.8/2.8	3.3	V	
Input Valtage	V _{IL}	GND	-	0.3VDDI O	V	
Input Voltage	V_{IH}	0.8 VDDIO	-	VDDIO	V	
Input leakage Current	I_{LKG}	-1		1	μΑ	

6.2 Backlight Driving Conditions

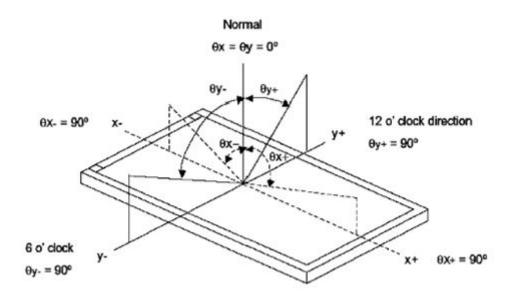
Itom	Symbol	Value			Unit	Remar	
Item	Symbol	Min.	Тур.	Max.	Unit	k	
Voltage for LED Backlight	V _F	-	12.8	-	V	I _L =20mA	
Current for LED Backlight	IL		20	-	mA		
Power Consumption	P		0.256		W		
LED Life Time		30,000			Hr	Note	

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃

7. Optical Characteristics

LINE	л	CVMDOI	CONDITIONS	SPEC	IFICAT	ΓΙΟΝS	LINIT	NOTE
ITEM		SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNIT	NOTE
Lumina	nce	L	I _L =20mA		350		Cd/m ²	
Contrast 1	Ratio	CR	θ=0°		400			
Response	Time	Ton+ Toff	25℃		30		ms	
	D 1	XR						
	Red	YR						
	Cmann	XG	Viewing normal angle					
CIE Color	Green	YG						
Coordinate	Blue	Хв						
	Blue	Yв						
	White	Xw			TBD			
	Wille	Yw			TBD			
	Hor.	$ heta_{\scriptscriptstyle X+}$			20			
Viewing	Пот.	$ heta_{\scriptscriptstyle X-}$	CR≥10		50		Dagraa	
Angle	Ver.	$ heta_{\scriptscriptstyle Y+}$	CK≠10		45		Degree	
	vei.	$ heta_{\scriptscriptstyle Y-}$			45			
Uniformity	Un			80			%	

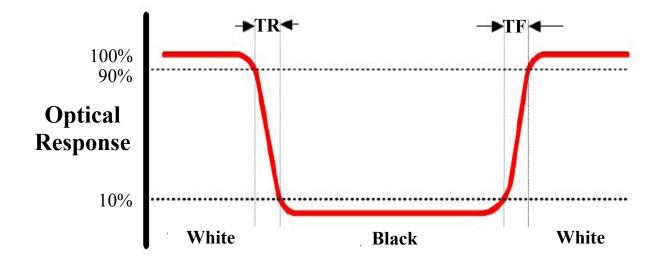
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

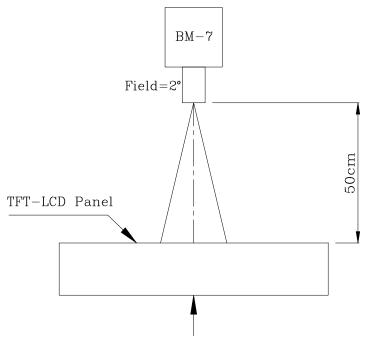
Note 3: Definition of Response Time(Tr,Tf)



Note 4: Definition of Luminance

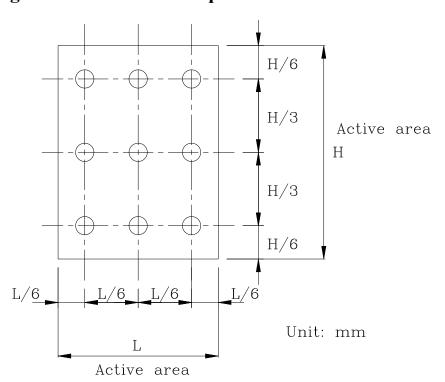
①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



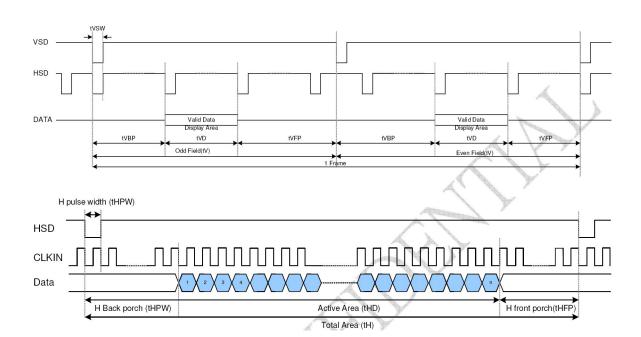
The center of the screen

2 The Brightness Test Point Setup



8. Timing Characteristics

8.1 RGB interface characteristic



Parameter	Symbol		Interface		Unit
Parameter	Symbol	Min.	Тур.	Max.	Onit
CLKIN frequency	/ fCLKIN	13.5	27	27.19	MHz
HSD period	tH	1024	1716	1728	CLKIN
HSD display period	tHD		960		CLKIN
HSD back porch	tHBP	50	70	255	CLKIN
HSD front porch	tHFP	14	686	718	CLKIN
HSD pulse width	tHSW	1	1	tHBP-1	CLKIN
VSD period time	tV	242.5	262.5	450.5	Н
Vertical display area	tVD		240		
VSD Odd field	tVBP	1	21	31	Н
back porch Even field	IVDP	1.5	21.5	31.5	П
VSD Odd field	tVFP	1.5	1.5	179.5	Н
front porch Even field	LVFF	1	1	179	П
VSD pulse width	tVSW	1CLKIN	1CLKIN	6H	
1 Frame		485	525	901	Н

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description			
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing i stand for 2 hours.			
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.			
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.			
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.			
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.			
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.			
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.			
08	Packing drop test	According to ASTM-D-5327.			
00	Electrical	Air: ± 4 KV 150pF/330 Ω 5 times			
09	Static Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time			

^{*}Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

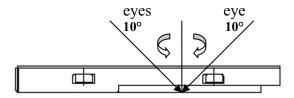
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

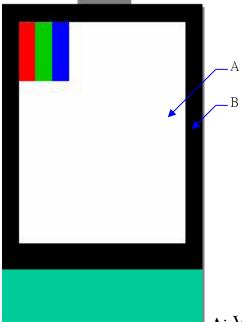
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5 °C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion				AQL
01	Electrical Testing	1.1 Missing vertical, ho 1.2 Missing character, d 1.3 Display malfunction 1.4 No function or no di 1.5 Current consumptio 1.6 LCD viewing angle 1.7 Mixed product types 1.8 Flicker	lot or icon. n. isplay. n exceeds p defect.			0.65
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 				2.5
03	LCD and Touch Panel black spots, white	3.1 Round type: As follows: $\Phi = (X+Y)/2$ * Densely spaced: No		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 2 2 1 0 spots within 3mm.	2.5
	spots, white spots, contaminati on (non – display)	3.2 Line type: (As follows)	Length(mm) L≤3.0 L≤2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5

NO.	Item	Criterion				
		If bubbles are visible, judge using black spot specifications, not easy	Size $\Phi(mm)$ $\Phi \leq 0.20$	Acceptable Q'ty Accept no dense		
04	Polarizer bubbles	to find, must check in	$0.20 < \Phi \le 0.50$	3	2.5	
	Dubbles	specify direction	$0.50 < \Phi \le 1.00$	2		
			1.00< Φ	0		
			Total Q'ty	3		
05	Scratches	Follow NO.3 -2 Line Type.	~			
06	Chipped glass	1 0 1	x : Chip leng $x \le 1/8a$ $1/3k$ $x \le 1/8a$ The total length of each $x \le 1/8a$ $x \ge 1/8a$	chip	2.5	

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion A				
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad: L Z L Z: Chip				
		y. Chip width X. Chip length thickness				
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$ $7.2.2$				
07	Glass crack	Non-conductive portion:	2.5			
		y: Chip width x: Chip length z: Chip thickness				
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$				
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack 				
		y: width x: length				
		$y \le 1/3L \qquad X \le a$				

NO.	Item	Criterion A				
14	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels: Z: Chip thickness y: Chip width x: Chip length					
		z: Chip thickness z≤t	y: Chip width ≤ 1/2 k and not over viewing area	x: Chip length x≤1/8a		
		○ Unit: mm○ If there are 2 or m	nore chips, x is the total	length of each chip		

NO.	Item	Criterion		
15	Touch Panel(Fish eye, dent and bubble on film)	SIZE(mm)Acceptable Q'ty $\Phi \le 0.2$ Accept no dense $0.2 < D \le 0.4$ 5 $0.4 < D \le 0.5$ 2 $0.5 < D$ 0	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5	
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65	

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD